



FPC

TE Internal #: 1-1734248-9

1 mm [.039 in] Centerline, Zero Insertion Force (ZIF), Vertical, Surface Mount, Stuffer Actuator, Gold Flash, 19 Position, FPC Connectors

[View on TE.com >](#)

Connectors > PCB Connectors > Wire-to-Board Connectors > FFC, FPC & Ribbon Connectors > FPC Connectors



Centerline (Pitch): 1 mm [.039 in]

Mating Retention Type: Zero Insertion Force (ZIF)

PCB Mount Orientation: Vertical

Termination Method to PCB: Surface Mount

FPC Actuator Type: Stuffer

Features

Product Type Features

|                                   |                                |
|-----------------------------------|--------------------------------|
| PCB Connector Assembly Type       | PCB Mount Receptacle           |
| Connector Product Type            | Connector Assembly             |
| Connector System                  | Flex-to-Board                  |
| Connector & Contact Terminates To | Flexible Printed Circuit (FPC) |
| FPC Actuator Type                 | Stuffer                        |

Configuration Features

|                                   |          |
|-----------------------------------|----------|
| Compatible With Wire & Cable Type | FFC, FPC |
| Number of Rows                    | 1        |
| PCB Mount Orientation             | Vertical |
| Number of Positions               | 19       |

Electrical Characteristics

|                   |         |
|-------------------|---------|
| Operating Voltage | 125 VDC |
|-------------------|---------|

Body Features

|                       |       |
|-----------------------|-------|
| Primary Product Color | Black |
|-----------------------|-------|

Contact Features

|                                                         |                |
|---------------------------------------------------------|----------------|
| PCB Contact Termination Area Plating Material Thickness | .025 μm[1 μin] |
| Contact Layout                                          | Inline         |
| Contact Type                                            | Socket         |



|                                                |                 |
|------------------------------------------------|-----------------|
| Contact Mating Area Plating Material Thickness | .025 µm[1 µin]  |
| Contact Shape & Form                           | Single Beam     |
| PCB Contact Termination Area Plating Material  | Gold            |
| Contact Base Material                          | Phosphor Bronze |
| Contact Current Rating (Max)                   | 1 A             |
| Contact Mating Area Plating Material           | Gold Flash      |

Termination Features

|                           |               |
|---------------------------|---------------|
| Termination Method to PCB | Surface Mount |
|---------------------------|---------------|

Mechanical Attachment

|                         |                            |
|-------------------------|----------------------------|
| Mating Alignment        | With                       |
| PCB Mount Alignment     | Without                    |
| PCB Mount Retention     | With                       |
| Connector Mounting Type | Board Mount                |
| Mating Retention Type   | Zero Insertion Force (ZIF) |

Housing Features

|                    |               |
|--------------------|---------------|
| Housing Material   | PA 9T         |
| Centerline (Pitch) | 1 mm[.039 in] |

Dimensions

|                              |                   |
|------------------------------|-------------------|
| Connector Length             | 26.4 mm[1.039 in] |
| Accepts Flex Cable Thickness | .3 mm[.012 in]    |
| Connector Height             | 7.7 mm[.303 in]   |
| Connector Width              | 4.6 mm[.181 in]   |

Usage Conditions

|                             |                          |
|-----------------------------|--------------------------|
| Operating Temperature Range | -20 – 85 °C[-4 – 185 °F] |
|-----------------------------|--------------------------|

Operation/Application

|                     |        |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Identification Marking

|                                |         |
|--------------------------------|---------|
| Circuit Identification Feature | Without |
|--------------------------------|---------|

Packaging Features

|                    |      |
|--------------------|------|
| Packaging Quantity | 1000 |
| Packaging Method   | Tape |



Product Compliance

For compliance documentation, visit the product page on TE.com>

|                                               |                                                                                                                                 |
|-----------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------|
| EU RoHS Directive 2011/65/EU                  | Compliant                                                                                                                       |
| EU ELV Directive 2000/53/EC                   | Compliant                                                                                                                       |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold                                                                                         |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JUNE 2024 (241)<br>Candidate List Declared Against: JUNE 2023 (235)<br>Does not contain REACH SVHC |
| Halogen Content                               | Not Low Halogen - contains Br or Cl > 900 ppm.                                                                                  |
| Solder Process Capability                     | Reflow solder capable to 260°C                                                                                                  |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) ‘Guidance on requirements for substances in articles’ posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

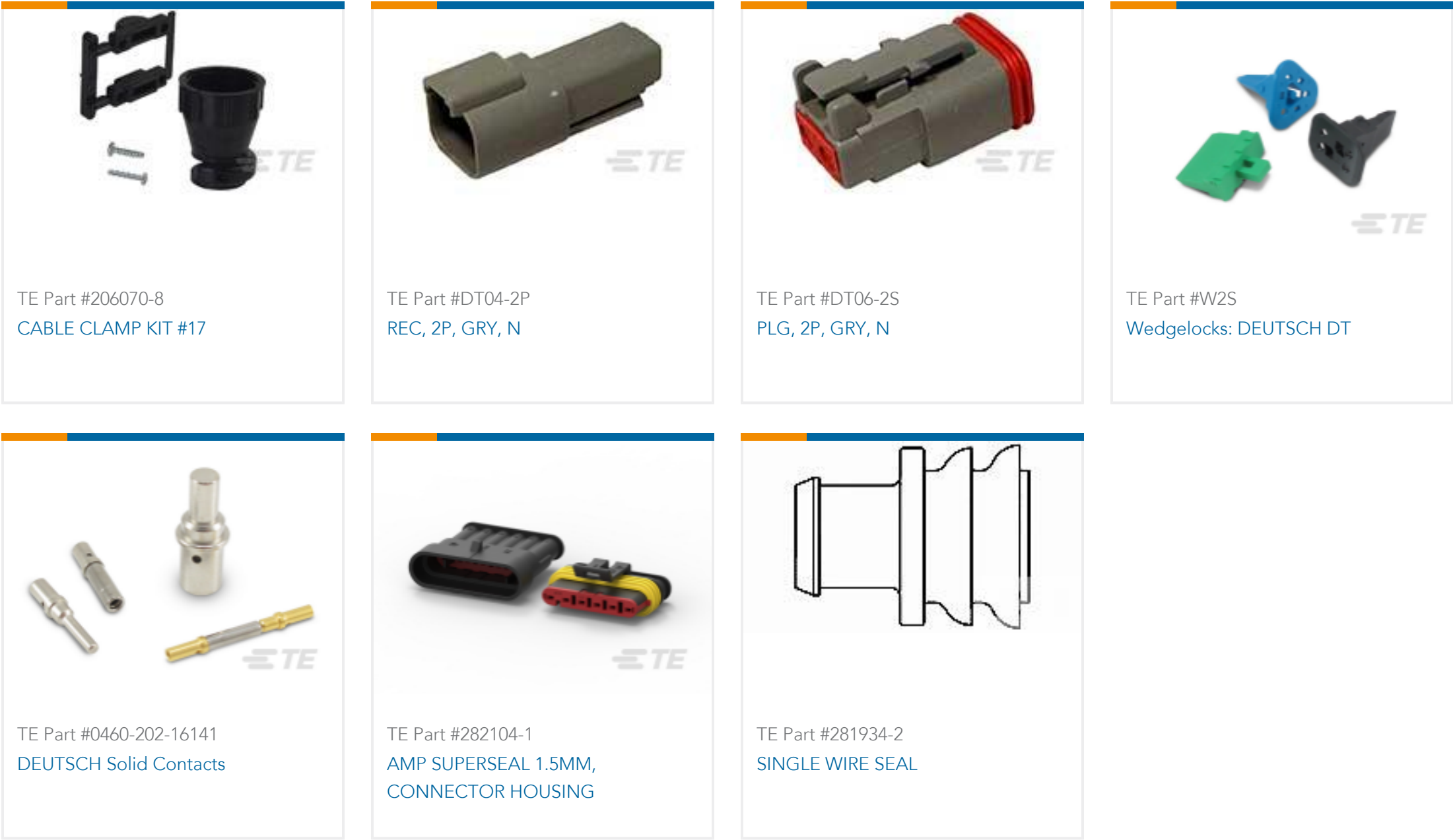


TE Part # 1-84952-9  
1MM FPC HORZ.BTTM CONT.ASS.19P



TE Part # 1-84982-9  
1MM FFC SMT V ASSY 19P EMBOSS

Customers Also Bought



Documents

Product Drawings

1.0 FPC, ZIF V/T, SMT, 19P

English

CAD Files

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_1-1734248-9\_E\_c-1-1734248-9-e.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_1-1734248-9\_E\_c-1-1734248-9-e.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_1-1734248-9\_E\_c-1-1734248-9-e.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

1-1773959-7-FPC-Connectors-CN

English

Product Specifications

Product Specification

English